

Immediate Release

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Banpil Announces Compatible Interconnect Library for Agilent's Advanced Design System EDA Software, Becomes Agilent Component Vendor Partner

Banpil Library enables high-speed and low-power designs, is available for free download

Santa Clara, California – October 9, 2007 - Banpil Photonics, Inc., a leading company in expanding the boundaries of optics and electronics through innovations, today announced the availability of its high-speed interconnect design simulation library that is compatible with Agilent Technologies Inc.'s Advanced Design System (ADS) Electronic Design Automation (EDA) software. The Banpil Interconnect Simulation Library (BISL) is a first of its kind library that enables system designers to design and simulate chip-to-chip, board-to-board, and rack-to-rack interconnects incorporating Banpil's patented metallic-interconnects capable of up to 40-Gb/s data transmission using conventional board materials (e.g. FR4). BISL will help engineers to evaluate system-level performance when connecting Banpil's interconnects with other components and help to increase performance by more than 6 times while significantly reducing power consumption by as much as 90% compared to conventional solutions.

BISL can be downloaded free of charge from Banpil's website at www.banpil.com/designtools.htm. It is packaged as a chip-to-chip interconnect family library making it easy for ADS users to install and use. BISL currently includes models of Banpil's interconnects on FR4-PCB for chip-to-chip, board-to-board, rack-to-rack, and soon flexible-printed-circuit (FPC) solutions. With the release of BISL, Banpil becomes an Agilent EEsof EDA Component Vendor Partner. Visit Agilent's partner website here http://eesof.tm.agilent.com/partners/vendor_libraries.html.

"I would like to welcome Banpil as the latest Agilent EEsof Component Vendor Partner," said Joe Civello, Platform Marketing Manager with Agilent's EEsof EDA division. "BISL adds to a rich set of simulation technologies in ADS by enabling designers to fully characterize and optimize 20-Gb/s and above designs for next generation applications in high-speed systems. System designers now can incorporate Banpil's breakthrough high-speed interconnects and other components into their familiar ADS integrated design environment for system and circuit simulation, along with schematic capture, layout, and verification capability."

"We are very pleased to become an Agilent Component Vendor Partner and helping engineers to design next generation high-speed systems," said Dr. Achyut Dutta, Banpil's CEO. "BISL is an important step for us because we are now able to provide system designers with first-hand opportunity to exploit, analyze, and verify tremendous performance enhancements that our high-speed interconnects are capable of providing. We previously announced breakthroughs in our metallic-interconnects requiring significantly less power to drive high-speed signals. We showed that Banpil interconnects can make >10-Gb/s signals in over 1.5-meter long rigid-FR4 printed-circuit-board (PCB) and >20-Gb/s in over 2-meters long FPC a reality that architects now can design, simulate, and implement into their practical systems applications, In addition, design-simulation results obtained using BISL are well correlated with experimental results."

BISL requires users to have ADS already installed on their computer and it is installed as an add-on simulation library. After designing and running simulations of Banpil high-speed interconnects, users need to contact Banpil at http://www.banpil.com/contact_us.htm regarding production implementation and licensing options. Banpil also welcomes opportunities to work with system vendors on new applications, and is actively seeking licensees, strategic partnerships with PCB and FPC manufacturers, and investors.

About Banpil Photonics, Inc.

Banpil Photonics develops and licenses fundamental technology expanding the boundaries of optics and electronics. The company has developed an extensive IP portfolio of high-speed interconnects, multispectral image-sensors, and high-efficiency photovoltaic technologies. Banpil innovations enable the development and manufacture of new generations of low-cost, high-speed electrical interconnects for

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chip-to-chip, board-to-board, and rack-to-rack applications; multispectral image-sensors for automotive and medical imaging, remote-sensing, and communication applications; and photovoltaic technology for solar cell applications. For more information, visit www.banpil.com.

About Agilent EEsof EDA Software

Agilent EEsof EDA is an industry leading provider of RF and microwave circuit and system design software, offering complete design integration for products such as cellular and portable phones, pagers, wireless networks, radar, satellite communications systems and high-speed digital wireline designs. Agilent's EEsof EDA software is compatible with and is used to design the company's test and measurement equipment. Additional information about all of Agilent's EDA software is available at www.agilent.com/find/eesof.

About Agilent Technologies

Agilent Technologies Inc. (NYSE: A) is the world's premier measurement company and a technology leader in communications, electronics, life sciences and chemical analysis. The company's 19,000 employees serve customers in more than 110 countries. Agilent had net revenue of \$5.0 billion in fiscal 2006. Information about Agilent is available on the Web at www.agilent.com.

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